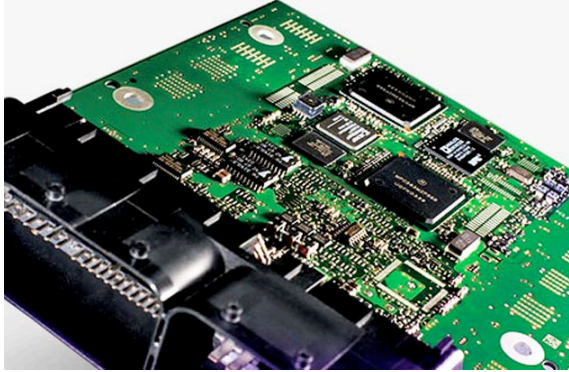


TG-NSP-60

Ultra conformable silicone-free putty type gap filler



Description

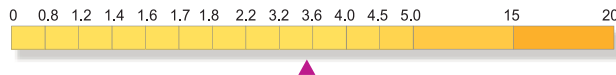
TG-NSP-60 is an ultra conformable silicone-free putty type gap filler. It is designed for when heat transfer is needed between delicate components where the pressure must be minimised and silicone contamination cannot be tolerated. TG-NSP-60 is designed to fill gaps from 0.25 – 8mm with little or no stress generated. The non-silicone formulation will adhere to all surfaces, such as metal housings, ceramic and plastic IC packages and FR4 boards to give a low thermal resistance path for heat transfer.

TG-NSP-60 is available in 30cc syringes, 6 and 12oz cartridges and 5 gallon pails.

Properties

- REACH Compliant
- RoHS Compliant

Thermal Conductivity: 5.9 W/mK
(W/mK - Z Axis)



Property	TG-NSP-60	Unit	Test Method
Colour	Grey	-	Visual
Thermal Conductivity	5.9	W/mK	ASTM D5470
Weight Loss	<0.5	%	ASTM E595
Working Temperature	-55 to 200	°C	-
Volume Resistivity	2.15×10^{15}	Ohm-cm	ASTM D-257
D4-10	0	PPM	GC / MS